

100V N-Channel Enhancement Mode MOSFET

Description

The PECN15N10G uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

General Features

- ◆ $V_{DS} = 100V$ $I_D = 15A$
 $R_{DS(ON)}(Typ.) = 82m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)}(Typ.) = 90m\Omega$ @ $V_{GS} = 4.5V$
- ◆ High density cell design for ultra low R_{dson}
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high E_{AS}
- ◆ Excellent package for good heat dissipation
- ◆ Special process technology for high ESD capability

Application

- ◆ Automotive applications
- ◆ Hard switched and high frequency circuits
- ◆ Uninterruptible power supply

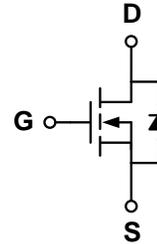
Package

- ◆ TO-252-2L

100% UIS TESTED!

100% ΔV_{ds} TESTED!

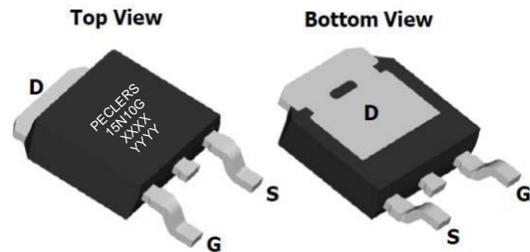
Schematic diagram



Marking and pin assignment

TO-252-2L

(Top View)



XXXX: Wafer Information

YYYY: Quality Code



Ordering Information

| Part Number | Storage Temperature | Package | Devices Per Reel |
|-------------|---------------------|-----------|------------------|
| PECN15N10G | -55°C to +150°C | TO-252-2L | 2500 |

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

| parameter | symbol | limit | unit |
|--------------------------------------|----------|----------|------|
| Drain-source voltage | V_{DS} | 100 | V |
| Gate-source voltage | V_{GS} | ±20 | V |
| Continuous Drain Current | I_D | TC=25°C | 15 |
| | | TC=100°C | 10 |
| Pulsed Drain Current | I_{DP} | 60 | A |
| Avalanche energy(L=0.5mH) | E_{AS} | 16 | mJ |
| Maximum power dissipation | TC=25°C | P_D | 50 |
| Operating junction Temperature range | T_j | -55—150 | °C |

Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit | |
|---|--------------|---------------------------------------|------------------|------|-----------|------------|---------|
| Static Characteristics | | | | | | | |
| Drain-source breakdown voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 100 | - | - | V | |
| Zero gate voltage drain current | I_{DSS} | $V_{DS}=100V, V_{GS}=0V$ | $T_J=25^\circ C$ | - | - | 1 | μA |
| | | | $T_J=85^\circ C$ | - | - | 30 | |
| Gate Leakage Current | I_{GSS} | $V_{DS}=0V, V_{GS}=\pm 20V$ | - | - | ± 100 | nA | |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 1 | 1.6 | 2.5 | V | |
| Drain-source on-state resistance ¹ | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=15A$ | - | 82 | 90 | m Ω | |
| | | $V_{GS}=4.5V, I_D=10A$ | - | 90 | 100 | | |
| On Status Drain Current | $I_{D(ON)}$ | $V_{DS}=5V, V_{GS}=10V$ | 10 | - | - | A | |
| Diode Characteristics | | | | | | | |
| Diode Continuous Forward Current | I_S | | - | - | 15 | A | |
| Reverse Recovery Time | t_{rr} | $I_F=15A,$ | - | 22 | - | ns | |
| Reverse Recovery Charge | Q_{rr} | $di/dt=100A/us$ | - | 90 | - | nC | |
| Dynamic Characteristics² | | | | | | | |
| Input capacitance | C_{ISS} | $V_{GS}=0V, V_{DS}=50V$ $f=1.0MHz$ | - | 884 | - | pF | |
| Output capacitance | C_{OSS} | | - | 77 | - | | |
| Reverse transfer capacitance | C_{RSS} | | - | 57 | - | | |
| Turn-on delay time | $t_{D(ON)}$ | $V_{GS}=10V, V_{DD}=50V, I_D=15A$ | - | 15 | - | ns | |
| Turn-on Rise time | t_r | | - | 5 | - | | |
| Turn-off delay time | $t_{D(OFF)}$ | | - | 25 | - | | |
| Turn-off Fall time | t_f | | - | 7 | - | | |
| Total gate charge | Q_g | $V_{GS}=10V, I_D=15A$ $V_{DS}=50V$ | - | 22 | - | nC | |
| Gate-source charge | Q_{gs} | | - | 3.34 | - | | |
| Gate-drain charge | Q_{gd} | | - | 2.98 | - | | |
| Drain-Source Diode Characteristics | | | | | | | |
| Diode forward voltage | V_{SD} | $I_{SD}=15A, V_{GS}=0V$ | - | 0.8 | 1.1 | V | |

Note: 1: Pulse test; pulse width $\leq 300ns$, duty cycle $\leq 2\%$.

2: Guaranteed by design, not subject to production testing.

Thermal Characteristics

| Parameter | Symbol | Typical | Unit |
|--|-----------------|---------|--------------|
| Thermal Resistance-Junction to Case | $R_{\theta JC}$ | 1.7 | $^\circ C/W$ |
| Thermal Resistance junction-to ambient | $R_{\theta JA}$ | 62.5 | |

Typical Performance Characteristics

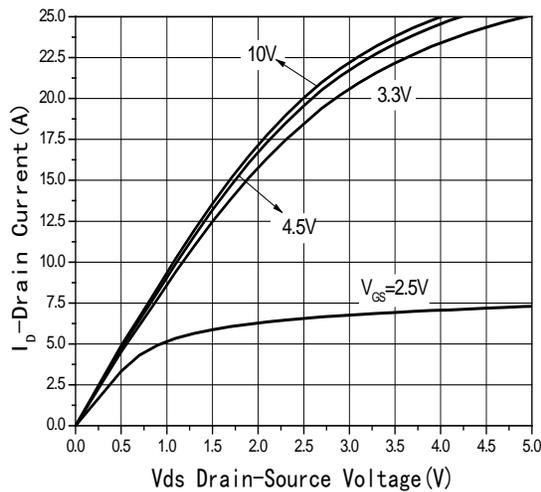


Fig1 Output Characteristics

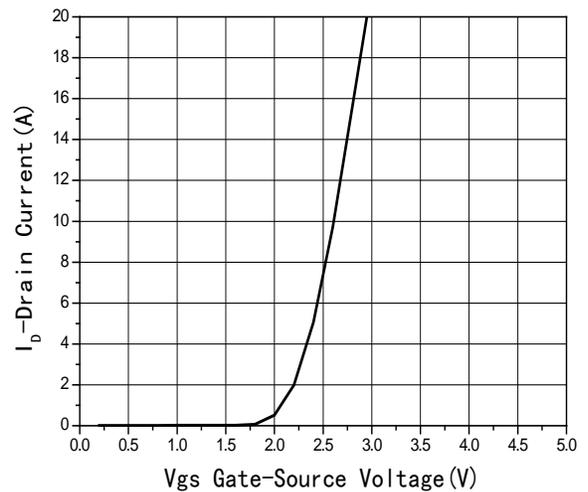


Fig2 Transfer Characteristics

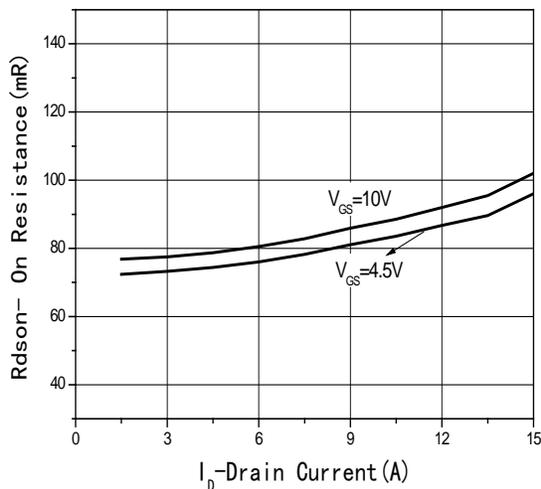


Fig3 Rdson-Drain current

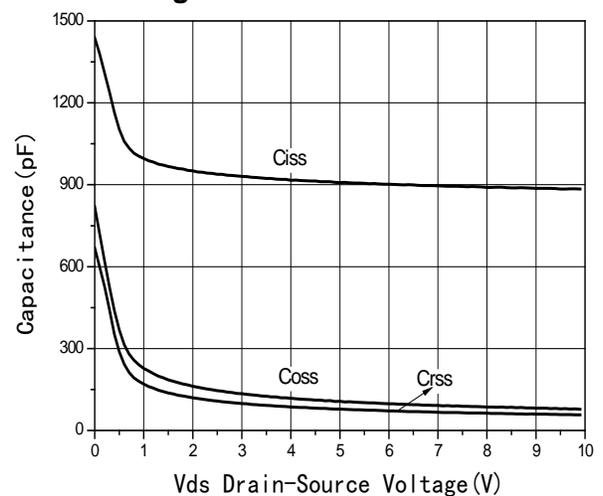


Fig4 Capacitance vs Vds

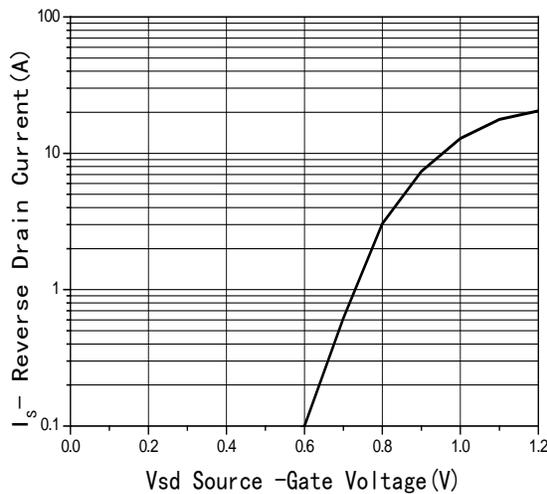


Fig5 Source-Drain Diode Forward

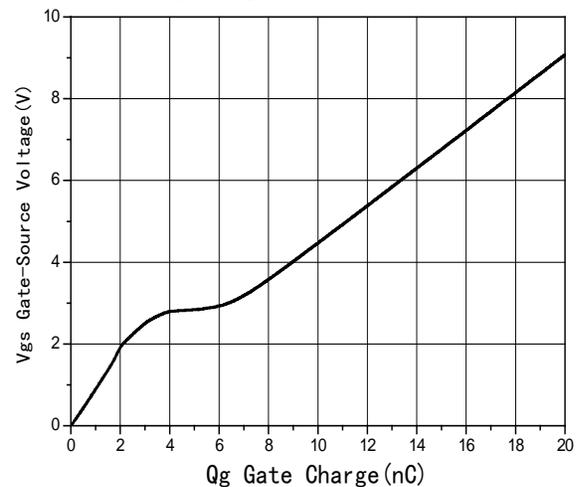


Fig6 Gate Charge

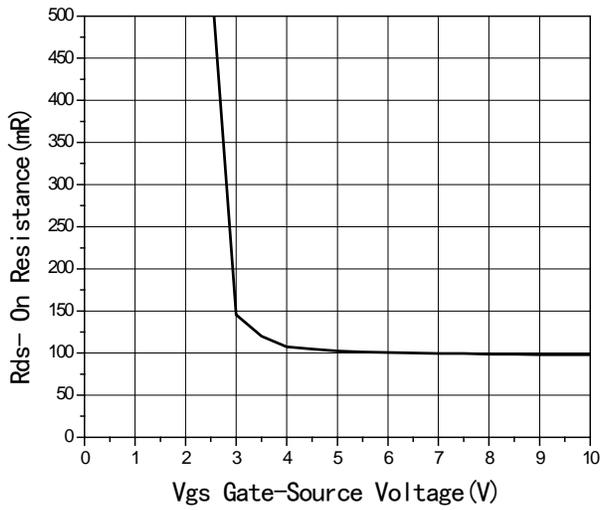


Fig7 Rds-on-Gate Drain voltage

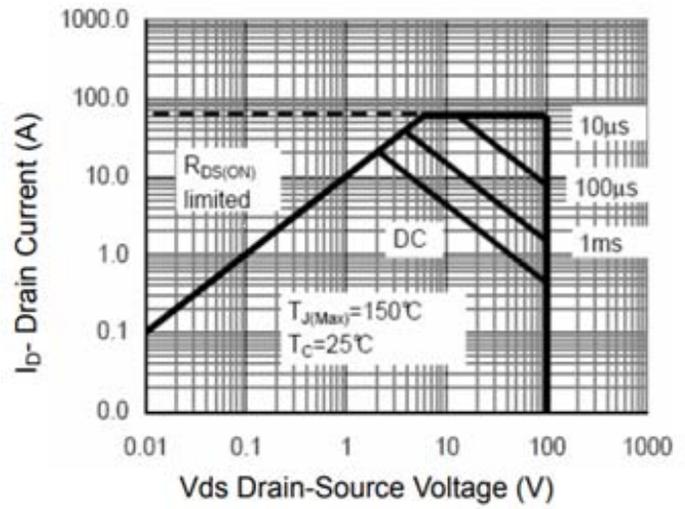


Fig8 Safe Operation Area

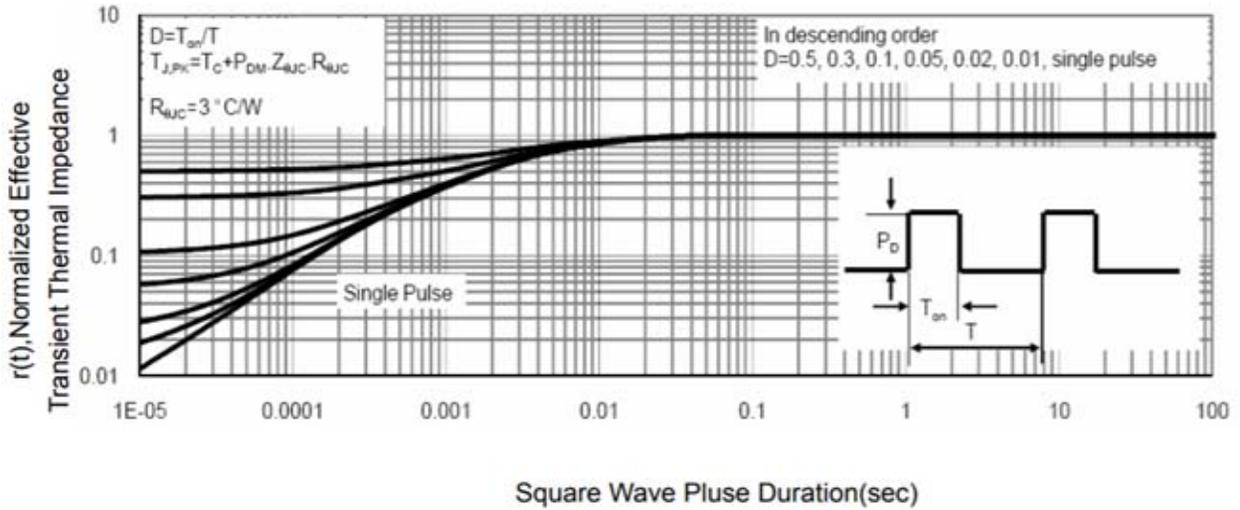


Fig9 Normalized maximum Transient Thermal Impedance

Figure A: Gate Charge Test Circuit & Waveforms

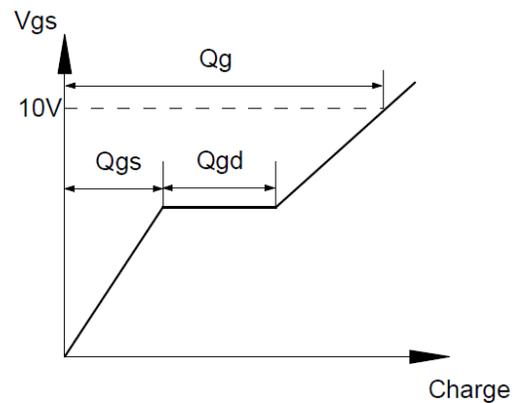
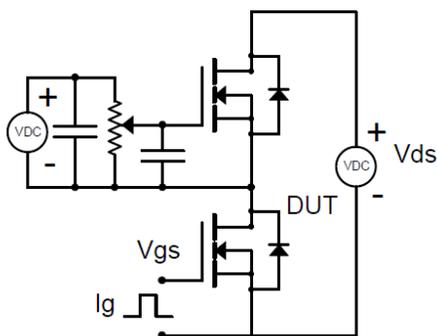


Figure B: Resistive Switching Test Circuit & Waveforms

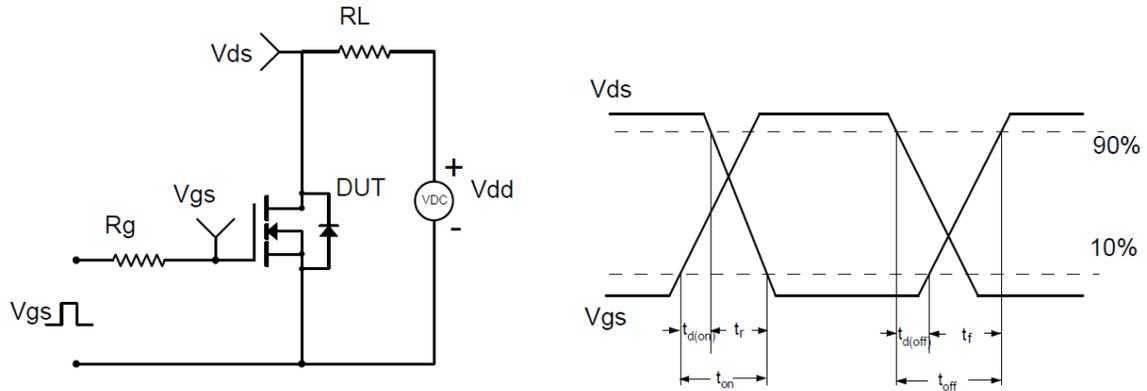


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

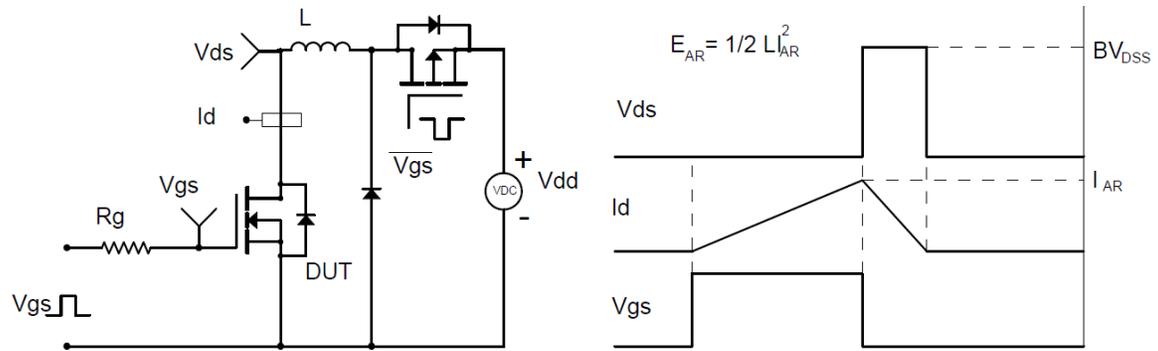
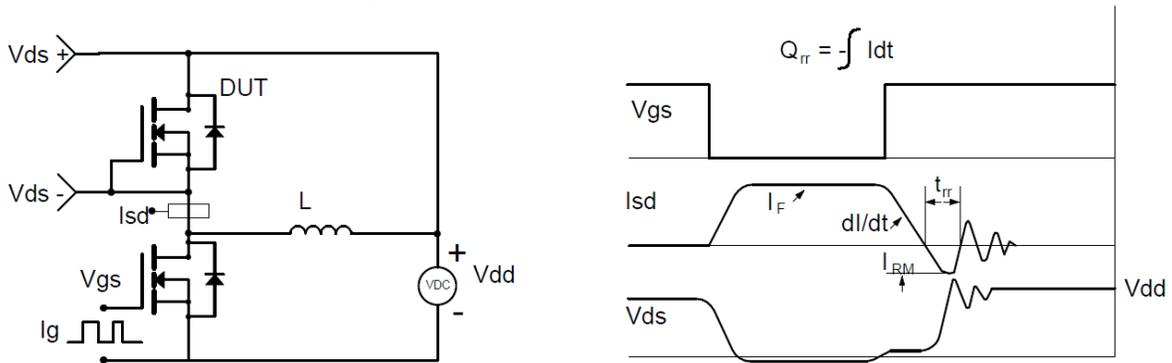
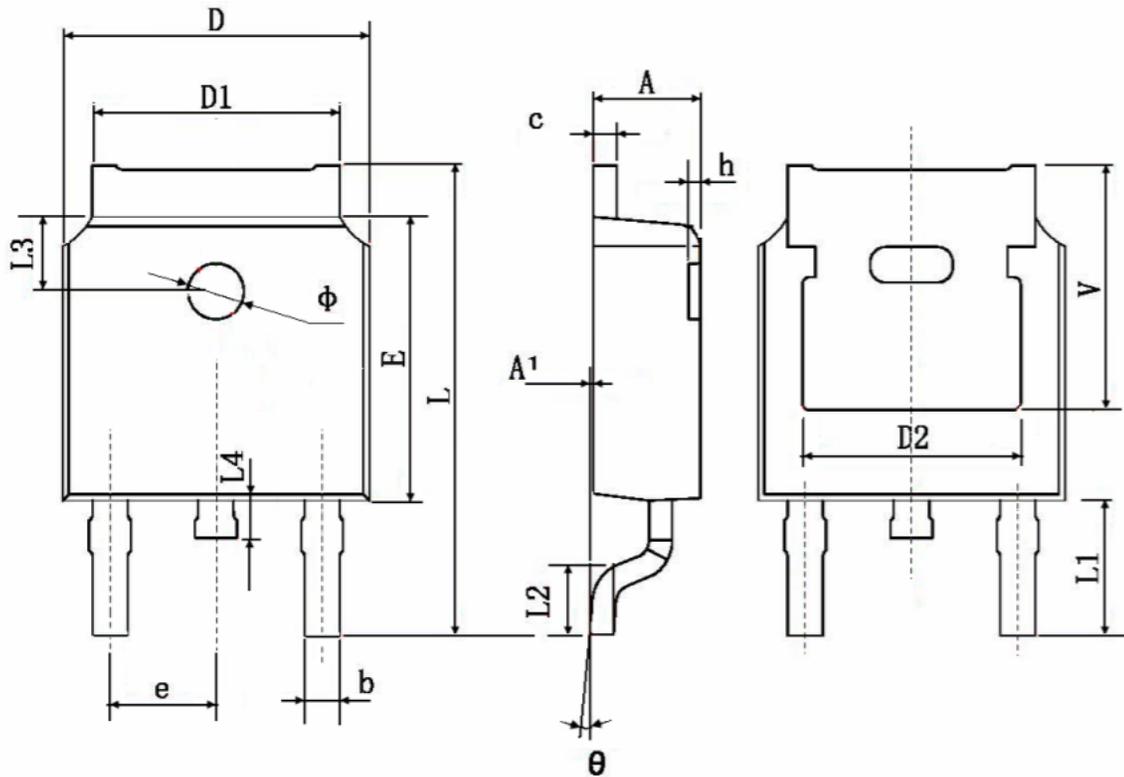


Figure D: Diode Recovery Test Circuit & Waveforms



Package Information

- TO-252-2L



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 |
| b | 0.660 | 0.860 | 0.026 | 0.034 |
| c | 0.460 | 0.580 | 0.018 | 0.023 |
| D | 6.500 | 6.700 | 0.256 | 0.264 |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 |
| D2 | 4.830 TYP. | | 0.190 TYP. | |
| E | 6.000 | 6.200 | 0.236 | 0.244 |
| e | 2.186 | 2.386 | 0.086 | 0.094 |
| L | 9.800 | 10.400 | 0.386 | 0.409 |
| L1 | 2.900 TYP. | | 0.114 TYP. | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 |
| L3 | 1.600 TYP. | | 0.063 TYP. | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 |
| φ | 1.100 | 1.300 | 0.043 | 0.051 |
| θ | 0° | 8° | 0° | 8° |
| h | 0.000 | 0.300 | 0.000 | 0.012 |
| V | 5.350 TYP. | | 0.211 TYP. | |